ROHS

LEADER TIME SRL

PRODUCT SPECIFICATION

16*2 Characters COB LCD MODULE MODEL: LT-1602E-608 Ver:1.1

< > > Finally Specification

CUSTOMER'S APPROVAL									
CUSTOMER:									
SIG	NATURE:	DATE:							

APPROVED	РМ	PD	PREPARED
BY	REVIEWD	REVIEWD	Ву

Prepared By: LEADER TIME SRL

VIA MONS. PROSDOCIMI, 27 36042 BREGANZE (VI)

• This specification is subject to change without notice. Please contact LT or it's representative before designing your product based on this specification.

Doc. No.:

Revision Status

Version	Revise Date	Page	Content	Modified By
VER 1.0	2011.04.28		First Issued	
VER 1.1	2011.11.16	4,5,6	Modify bias, and VO,BLU	

Doc. No.:

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1. Features

The features of LCD are showed as follows

* Display mode : FSTN/Transflective/Positive * Controller IC : AIP31066(English-Japanese)

* Display format : 16X2Characters * Interface Input Data : 4 Bit or 8 Bit

* Driving Method : 1/16Duty, 1/5Bias

* Viewing Direction :12 O'clock

* Backlight : LED White (Side)

*Sample NO. : EC1602A4FSW7B-BC_01/20110620

2. MECHANICAL SPECIFICATIONS

Item Specification	on	Unit
Module Size	122(W) x44(H) x13.3Max(T)	mm
Viewing Area	99(W) x 25(H)	mm
Activity Display Area	94.84(W)x19.56(H)	mm
Character Font	5x8 Dots	-
Character Size	4.84(W)x9.22(H)	mm
Character Pitch	6(W)x10.34(H)	mm
Dot Size	0.92(W)x1.1 (H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Min	Max	Unit
Supply Voltage For Logic	Vdd	-0.3	7.0	V
Supply Voltage For LCD Drive	V_{LCD}	VDD-15.0	V _{DD} +0.3	V
Input Voltage	Vin	-0.3	V _{DD} +0.3	V
Operating Temp.	Тор	20	+70	°C
Storage Temp.	Tst	-30	+80	°C

^{*.} NOTE: The response time will be extremely slow when the operating temperature is around -10° C, and the back ground will become darker at high temperature operating.

3-2 ELECTRICAL CHARACTERISTICS

Item	Sy	mbol	Test Condition	Min. T	yp.	Max.	Unit
Logic supply	Voltage	VDD — Vss		4.5	5	5.5	V
LCD Dri	ve	V_{LCD}	Ta = 25 °C	4.2	4.5	4.8	V
Input Voltage	"H" Level	V_{IH}	V _{DD} =5V ± 10%	2.2	-	VDD	V
	"L" Level	V _{IL}			-	0.6	V
Frame Freq	Frame Frequency			-	80	-	-
Current Cons	umption	I _{DD}		-	2	-	mA

3-3 BACKLIGHT

3-3-1. Absolute Maximum Ratings

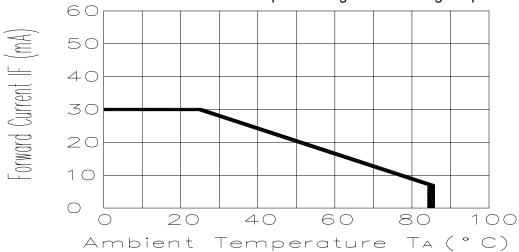
Item Sy	mbol	Condition	Min.	Тур.	Max.	Unit
Forward Current	IF		-	24	30	mA
Reverse Voltage	VR	Ta = 25 °C	-	-	5	V
Power Dissipation	PD		-	-	270	mW

3-3-2. Electrical-optical Characteristics

Item Sy	mbol	Condition	on Min.		Ту	η.	Ma	Unit	
Forward Voltage	VF			-	4.	.5	-	-	V
Average Luminous Intensity	lv	If=24mA Ta = 25 °C		_ 200		00	-		cd/m ²
Color Coordinate	-		X 0.25	Y 0.25	X 0.29	Y 0.29	X 0.33	Y 0.33	-

This brightness is measured without LCD panel.

For operation above 25 °C,The lfm & Pd must be derated , the current derating is -0.36mA/ °C for DC drive and -0.86mA/ °C for Pulse drive ,the Power dissipation is -0.75mW/ °C.The product working current must not more than the 60% of the lfm or lfp according to the working temperature.



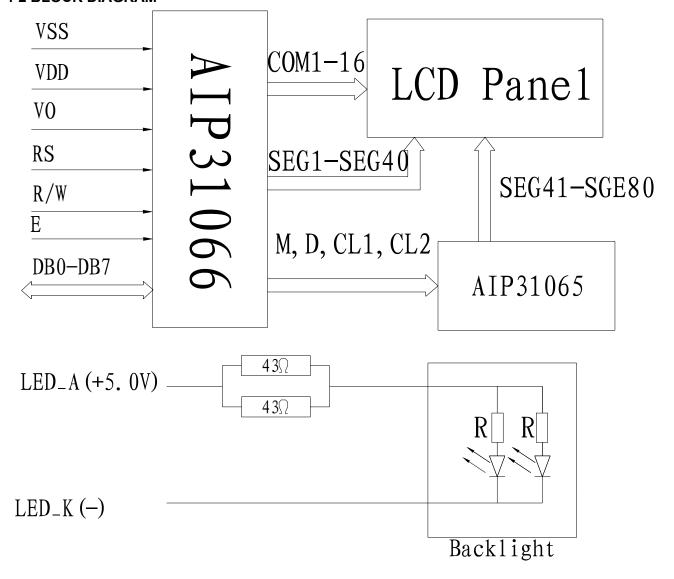
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4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1 INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCIONS
1	LED_K	Backlight (-)
2 LED	_A	Backlight (+)
3 VSS		Ground
4	VDD	Supply voltage for logical circuit
5	V0	Supply voltage for LCD driving
6	RS	A signal for selecting registers. 1: Data Register (for read and write) 0: Instruction Register (for write)
7	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
8	E	A enable signal for reading or writing data.
9-16	DB0~DB7	8 Bit Data Bus

4-2 BLOCK DIAGRAM



5. TIMING CHARACTERISTICS

AC Characteristics ($V_{DD} = 4.5V \sim 5.5V$, Ta = -30 \sim +85°C)

Mode	Characteristic	Symbol	Min.	Тур.	Max.	Unit
	E Cycle Time	tc	500	-	-	
Write Mode (Refer to Fig-1)	E Rise / Fall Time	t_R, t_F	-	-	20	
	E Pulse Width (High, Low)	t _w	230	-	-	
	R/W and RS Setup Time	t _{su1}	40	-	-	ns
	R/W and RS Hold Time	t _{H1}	10	-	-	
	Data Setup Time	t _{su2}	80	-	-	
	Data Hold Time	t _{H2}	10	-	-	
	E Cycle Time	t _c	500	-	-	
	E Rise / Fall Time	t _R , t _F	-	-	20	
	E Pulse Width (High, Low)	t _w	230	-	-	
Read Mode	R/W and RS Setup Time	t _{su}	40	-	-	ns
(Refer to Fig-2)	R/W and RS Hold Time	t _H	10	-	-	
	Data Output Delay Time	t _D	-	-	120	
	Data Hold Time	t _{DH}	5			

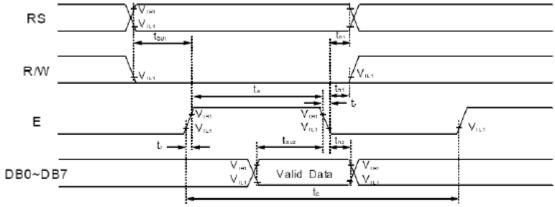


Figure 1 . Write Mode Timing Diagram

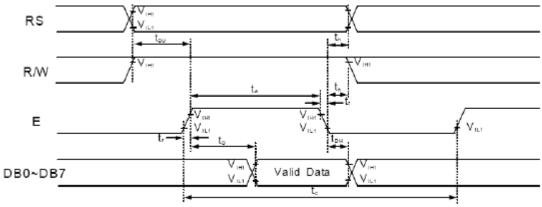


Figure 2 . Read Mode Timing Diagram

6. COMMAND LIST

Instruction				Ins	tructi	on Co	ode				Description	Execution
	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Instruction Code	time(fsoc=270)
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC.	1.53ms
Return Home	0	0	0	0	0	0	0	0	1	Х	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and make shift of entire display enable.	39μs
Display ON/OFF Control	0	0	0	0	0	0	1	D	С	В	Set display(D), cursor(C), and blinking of cursor(B) on/off control bit.	39μs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	X	X	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.	39µs
Function Set	0	0	0	0	1	DL	N	F	X	X	Set interface data length (DL: 4-bit/8-bit), numbers of display line (N: 1-line/2-line), display font type (F: 5 X 8 dots/ 5 X 11 dots)	39μs
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39µs
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	39μs
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0μs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	43µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	43µs

NOTE: When an MPU program with checking the Busy Flag (DB7) is made, it must be necessary 1/2 fosc is necessary for executing the next instruction by the falling edge of the 'E' signal after the Busy Flag (DB7) goes to "LOW".

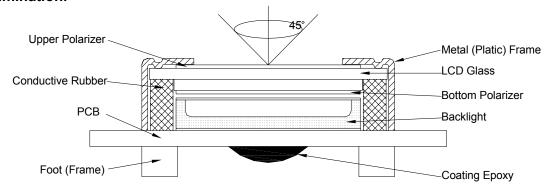
7. CHARACTER GENERATOR ROM

Lever Bits	00 00 00 01	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1 101	1110	1111
xxxx0000	CG RAM (1)		0	9	P	1	F				-	9	Ę	Ċζ	þ
xxxx0001	(2)	!	1	A	Q	а	9			0	7	Ŧ	4	ä	q
xxxx0010	(3)	Ш		В	R	b	r				1	ŋ	×	ß	0
xxxx0011	(4)	#	3	C	5	C	s			_	Ż	Ŧ	ŧ	ε	8
xxxx0100	(5)	\$	4	D	Ţ	d	ŧ.				I	ŀ	þ	H	G
xxxx0101	(6)	7	5	E	U	e	u				7	†	1	5	ü
xxxx0110	(7)	&	6	F	Ų	f	Ų			7	Ħ	T	3	ρ	Σ
xxxx0111	(8)	7	7	G	W	9	W			7	‡	Z	7	9	π
xxxx1000	(1)	(8	H	X	h	X			4	7	*	IJ	Ţ	X
xxxx1001	(2))	9	I	Y	i	y			Ċ	ጎ	Į	ιb	-1	У
xxxx1010	(3)	*	•	J	Z	j	Z			I		'n	ļ.	j	Ŧ
xxxx1011	(4)	+	;	K		k	{			#	Ħ	t		×	F
xxxx1100	(5)	,	<		¥	1				ħ	Ð	7	7	¢.	Ħ
xxxx1101	(6)	_	=	M]	M	}			ユ	Z	^	_,	Ł	·ŀ
xxxx1110	(7)	•	>	N	۸	n	+			3	t	#	**	ħ	
xxxx1111	(8)	/	?	0	_	0	+			'n	y	7		Ö	

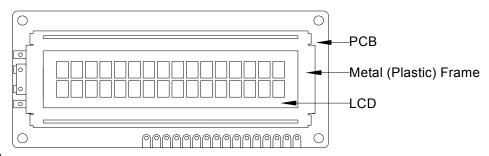
Note: The user can specify any pattern for character-generator RAM.

8. QUALITY SPECIFICATIONS

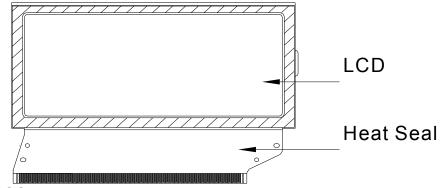
- 8 1. LCM Appearance and Electric inspection Condition
- 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



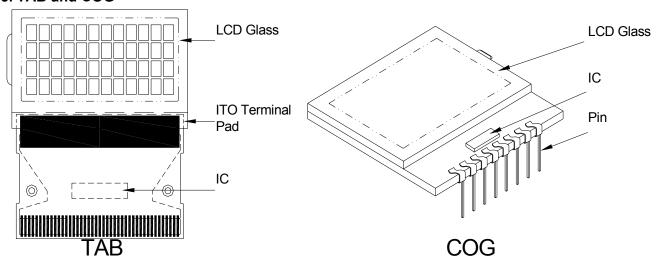
- 2. View Angle: with in 45° around perpendicular line.
- 8-2. Definition
- 1. COB



2. Heat Seal



3. TAB and COG



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8-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (||) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.65%Minor defect: AQL = 1.5%

8-4. Criteria

1. COB

Defect	Inspection Item	Inspection Standards			
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject		
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject		
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject		
Major	PCB cutting defect	Exceed the dimension of drawing	Reject		

2. SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift component soldering pad X D Y	X < 3/4Z Y > 1/3D	Reject
Minor	Component tilt component soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD ← PCB	θ <u><</u> 20°	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	Inspection Standards			
Major	Crack / breakage	Any	/where	Reject	
		W	L	Acceptable of Scratch	
		w<0.1mm	Any	Ignore	
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2	
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1	
_		w <u>></u> 0.3mm	Any	0	
		with distance g	e criteria applicable reater than 5mm. on the back sid ignored.		
		,		Acceptable of Dents / Pricks	
		Ф <u><</u> 1.0mm		2	
	Frame Dent , Prick	1.0<4	1		
Minor	$\Phi = \frac{L + W}{2}$	1.5	0		
	2	Note: 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored			
Minor	Frame Deformation	Exceed the dimension of drawing			
Minor	Metal Frame Oxidation	Any rust			

4. Flexible Film Connector (FFC)

4. Flexible Film Connector (FFC)								
Defect	Insp	ection Item	Inspection Standards					
Minor	Tilte	d soldering	Within the angle +5°	Acceptable				
Minor	Uneven solder joint /bump			Reject				
			Expose the conductive line	Reject				
Minor	Hole	$\Phi = \frac{L + W}{2}$	Φ > 1.0mm	Reject				
Minor	Position shift		Y > 1/3D	Reject				
WIITIOT		- - - - - - - - - -	X > 1/2Z	Reject				

5. Screw

Defect Inspection Item		Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

6. Heatseal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Ф> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
Minor		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

. LED Backing Protective Film and Others							
Defect	Inspection Item	Inspection Standards					
		Acceptable number of units					
		Ф <u><</u> 0.10mm	ignore				
		0.10<Ф <u><</u> 0.15mm	2				
Minor	LED dirty, prick	0.15<Φ <u><</u> 0.2mm	1				
		Ф>0.2mm	0				
		The distance between any two spots should be ≥5 Any spot/dot/void outside of viewing area is accep					
Minor	Protective film tilt	Not fully cover LCD					
Major	COG coating	Not fully cover ITO circuit	Reject				

8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

9. Inspection Specification of LCD

Defect	Inspect Item				Ins	spection	St	andards	5	
	<u> </u>	* Glass Scratch	W		W <u><</u>	0.03	0.0	0.0 <u><</u> 0.0	5 \\	V>0.05
		* Polarizer Scratch	L		L٠	<5		L<3		Any
Minor	Linear Defect	* Fiber and Linear	ACC. NO.	1			1		Reject	
		material	Note	L is the length and W			/ is th	e width of	the de	efect
		* Foreign material		Φ <u><</u> 0		0.1<Φ <u><</u> 0	.15 (0.15<Ф <u><</u> 0.	.2	Ф>0.2
	Black Spot and			3EA 100m	\ / im²	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note		Φ is the average diameter of the Distance between two defects					
		* Unobvious			Φ <u><</u> (0.3	0.3	<Ф <u><</u> 0.5	0	.5<Ф
	White Spot	transparent foreign material between	NO.	3EA	\ / 10	00mm ²		1		0
Minor	and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note	Φ is the average diameter of the defect. Distance between two defects > 10mm.						
	Segment Defect		Ф	Ф <u><</u> 0.	10	0.10<Φ <u><</u>	0.20	0.20<Φ <u><</u>	0.25	Ф>0.25
		<u> </u>	ACC. NO.	3EA 100m	m ²	2		1		0
Minor		-W-		W is more than 1/2 segment width Rej				Reject		
			Note	te $\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm			m			
			Ф	Ф <u><</u> 0.	10	0.10<Ф<	0.20	0.20<Ф<	0.25	Ф>0.25
	Protuberant	w W	W	Glue		W <u><</u> 1/2 \$ W <u><</u> 0.	Seg	W <u><</u> 1/2 · W≤0.	Seg	Ignore
Minor	Segment	$\Phi = (L + W)/2$		3EA 100m		2		1		0
			1. Seg	ment						
			E	3	B <u><</u>	0.4mm	0.4 <e< td=""><td>3<u><</u>1.0mm</td><td>B>′</td><td>1.0mm</td></e<>	3 <u><</u> 1.0mm	B>′	1.0mm
Minor	Assembly		B-			A<1/2B		A<0.2		<0.25
	Mis-alignment	HB-1 -1 HA	Judge Acceptable Acceptable Acceptable					eptable		
			2. Dot	Matrix						1
			Deformation>2°				Reject			
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"							

9. RELIABILITY

NO.	Item	Condition	Criterion		
1	High Temperature Operating	70℃, 96Hrs			
2	Low Temperature Operating	-20℃, 96Hrs			
3	High Humidity	50℃, 90%RH, 96Hrs			
4	High Temperature Storage	80℃, 96Hrs			
5	Low Temperature Storage	-30℃, 96Hrs	No defect in cosmetic and		
		Random wave	operational function allowable.		
6	Vibration	10 ~ 100Hz	Total current Consumption shoul be below double of initial value.		
0	VIDIALIOII	Acceleration: 2g			
		2 Hrs per direction(X,Y,Z)			
		-20℃ to 25℃ to 70℃			
7	Thermal Shock	(60Min) (5Min) (60Min)			
		16Cycles			
Ω	ESD Testing	Contract Discharge Voltage: +1 ~ 5kV and –1 ~ –5kV	There will be discharged ten times at every discharging		
8	Lob resung	Air Discharge Voltage: +1 ~ 8kV and –1 ~ -8kV	voltage cycle. The voltage gap is 1kV.		

Note: 1) Above conditions are suitable for our company standard products.
2) For restrict products, the test conditions listed as above must be revised.

10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers, which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Tricolor trifler thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Kenton
- Aromatics

(3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's .which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- -A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

In the case of storing for a long period of time, (For years) for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later. When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

Issued Date: 2011.11.16 Doc. No.: 11. OUTLINE DIMENSION APPROVED Pin assignment LED 982 1980 a NSS RS DB7 15 10 7 133 REVISION RECORD First Issue 2011.04.27 m m DRAW UNIT BYCK 1.60 KEV. →+13.30 max + 1/1 ∢ # -6.00 -4.84 8.70±0.3 **FRONT** I. 10-91.1 0.98 9, 22--10.34inject port 44.0±0.5 9.5 .8.0±0.78 \oplus $4-\phi 3.5$ Viewing direction 2.50-(V. A.) 99.0±0.2 -122.0 ± 0.5 -115.0 ± 0.3 -104.40 ± 0.3 $16-\phi 1.0$ (A. A. 94. 84)- $-11.0 - - 12.54x(16-1) = 38.1 \pm 0.1 \bigoplus$ \oplus (10.22) →(8. 19. 56) 6.0±08.7− - (V. A) 25. 00 ± 0. 2--35.40±0.2-